

**Call for Papers – SIITME 2013**

Dear Colleagues,

The organizing committee of SIITME 2013 kindly invites you to submit an abstract/paper to the **2013 IEEE 19<sup>th</sup> International Symposium for Design and Technology in Electronic Packaging (SIITME)**. The scientific event will take place in Galați, the largest Romanian harbour on Danube, on **October 24<sup>th</sup>–27<sup>th</sup>, 2013**. **Web page:** <http://www.siidme.ro>

**SUBMISSION OF ABSTRACTS AND PAPERS:**

Interested authors are invited to submit a two-page abstract according to the **template**, as MS-Word document, Version 97 or later, and as PDF document, **attached to an e-mail to [siitme@siitme.ro](mailto:siitme@siitme.ro)**.

**Papers meeting the quality criteria will be included in the IEEE Xplore Digital Library.**

**Abstracts and papers** will be reviewed by the international Scientific Committee.

1. Each abstract will be reviewed on:
  - suitability for one of the topics of the conference
  - scientific content and level, and the relevance of presented results;
  - correspondence with the abstract template, English usage and grammar.Authors of accepted abstracts will be invited to submit a full-length conference paper according to the conference paper template.
2. Papers meeting the following criteria will be published in the Conference Proceedings and will be available through IEEE Xplore:
  - the comments of the reviewers have been taken into consideration;
  - originality of the paper<sup>1</sup> is given;
  - it corresponds with the paper template, English usage and grammar are correct,
  - signed IEEE copyright form has been submitted.

**TOPICS**

- A. Emerging Technologies & Trends in Advanced Packaging
- B. Power Electronics and Microsystems Packaging
- C. Assembly and Manufacturing Technology
- D. Design of Electronic Circuits and Systems
- E. Electronics Simulation & Modelling
- F. Electronics Applications
- G. Optoelectronics & Advanced Communication Packaging
- H. Applied Reliability
- I. Challenge in Global Education

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**IMPORTANT DATES:**

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| Submission of abstracts:   | September 1st, 2013  |
| Notification of abstract acceptance:                             | September 22nd, 2013 |
| Submission of camera-ready papers and copyright forms:           | October 6th, 2013    |
| Notification of paper acceptance:                                | October 13th, 2013   |
| Confirmation of registration and submission of e-copyright form: | October 17th, 2013   |

<sup>1</sup> The originality of papers will be checked by the iThenticate plagiarism detection and prevention software.